# EA2532 Series



DRC

# REGULATORY COMPLIANCE

#### **ITEM DESCRIPTION**

Mode of Operation

**Spurious Response** 

Insulation Resistance

Storage Temperature Range

**Drive Level** 

**Crystal Cut** 

Quartz Crystal Resonator 2.5mm x 3.2mm x 0.8mm 4 Pad Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS		
Nominal Frequency	10MHz to 54MHz	
Frequency Tolerance/Stability	$\frac{1}{10000000000000000000000000000000000$	
	±10ppm at 25°C, ±10ppm over 0°C to +70°C ±10ppm at 25°C, ±10ppm over -20°C to +70°C	
Aging at 25°C	±3ppm/year Maximum	
Load Capacitance	Series Resonant, 8pF Parallel Resonant to 30pF Parallel Resonant	
Shunt Capacitance	5pF Maximum	
Equivalent Series Resistance	250 Ohms Maximum over Nominal Frequency of 10MHz to 11.9999999MHz 150 Ohms Maximum over Nominal Frequency of 12MHz to 13.9999999MHz 100 Ohms Maximum over Nominal Frequency of 14MHz to 15.9999999MHz 80 Ohms Maximum over Nominal Frequency of 16MHz to 19.9999999MHz 60 Ohms Maximum over Nominal Frequency of 20MHz to 29.9999999MHz 50 Ohms Maximum over Nominal Frequency of 30MHz to 53.9999999MHz	

35 Ohms Maximum over Nominal Frequency of 54MHz to 54MHz

AT-Cut Fundamental

100µWatts Maximum

-3dB Minimum

-40°C to +150°C

Measured at 100Vdc 500 Megaohms Minimum

Measured from Fo to Fo +5000ppm

AT-Cut

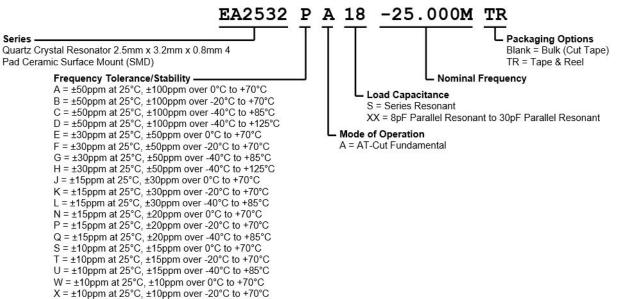
## EA2532 Series

Series

#### PART NUMBERING GUIDE

X = ±10ppm at 25°C, ±10ppm over -20°C to +70°C



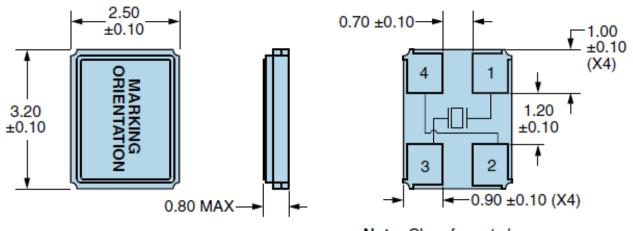


A = AT-Cut Fundamental

Seam Sealed



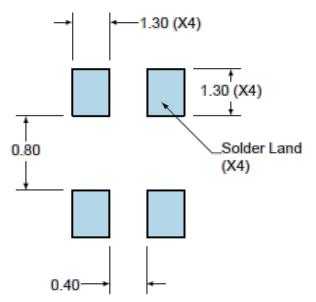
#### **MECHANICAL DIMENSIONS**



Note: Chamfer not shown.

Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm).

#### SUGGESTED SOLDER PAD LAYOUT



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

All Tolerances are ±0.1

#### **All Dimensions in Millimeters**

## EA2532 Series

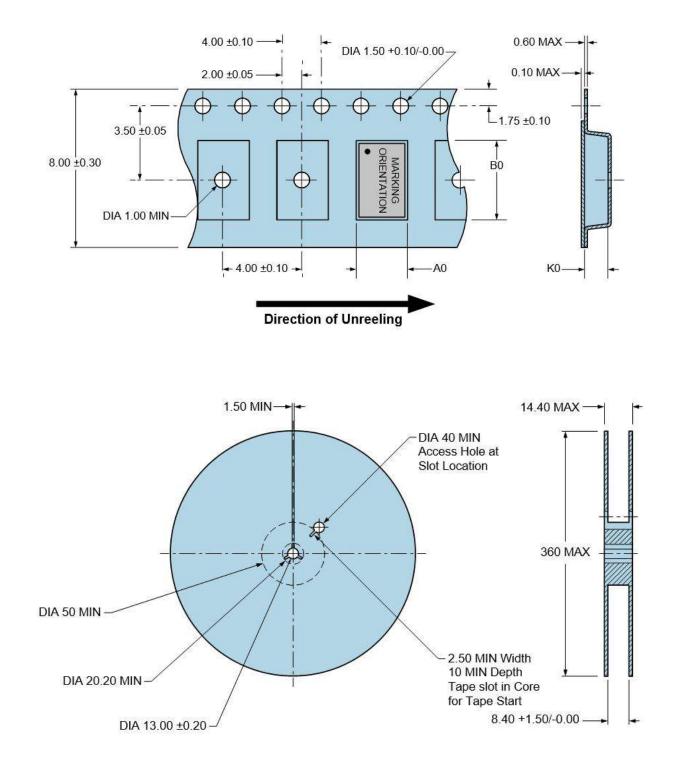


#### **TAPE & REEL DIMENSIONS**

Quantity per Reel: 1,000 Units

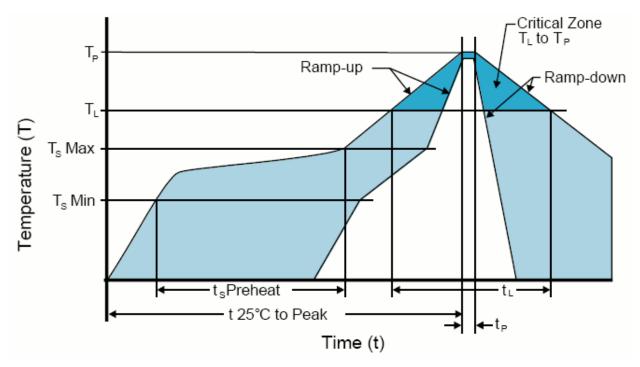
All Dimensions in Millimeters

Compliant to EIA-481





### **RECOMMENDED SOLDER REFLOW METHODS**



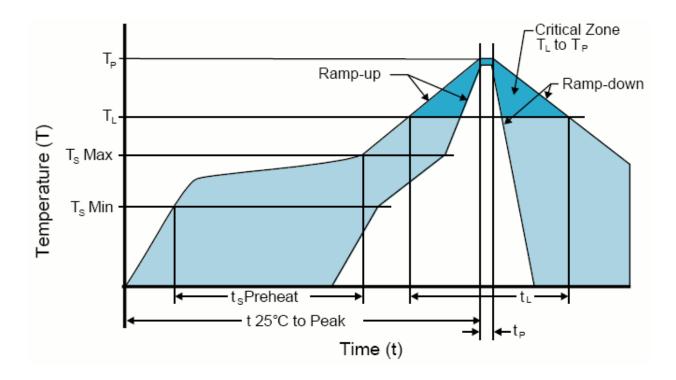
HIGH TEMPERATURE INFRARED/CONVECTION		
Ts MAX to T∟ (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (Ts MIN)	150°C	
- Temperature Typical (Ts TYP)	175°C	
<ul> <li>Temperature Maximum(Ts MAX)</li> </ul>	200°C	
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds	
Ramp-up Rate (T⊾ to Tթ)	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T∟)	217°C	
- Time (t∟)	60 - 150 Seconds	
Peak Temperature (T <sub>P</sub> )	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(TP Target)	250°C +0/-5°C	
Time within 5°C of actual peak ( $t_p$ )	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

#### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



## **RECOMMENDED SOLDER REFLOW METHODS**



LOW TEMPERATURE INFRARED/CONVECTION		
Ts MAX to T∟ (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
<ul> <li>Temperature Minimum (Ts MIN)</li> </ul>	N/A	
<ul> <li>Temperature Typical (Ts TYP)</li> </ul>	150°C	
<ul> <li>Temperature Maximum(Ts MAX)</li> </ul>	N/A	
- Time (t <sub>s</sub> MIN)	30 - 60 Seconds	
Ramp-up Rate (T⊾ to T <sub>P</sub> )	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T∟)	150°C	
- Time (t∟)	200 Seconds Maximum	
Peak Temperature (T <sub>P</sub> )	245°C Maximum	
Target Peak Temperature(T <sub>P</sub> Target)	245°C Maximum 2 Times/230°C Maximum 1Time	
Time within 5°C of actual peak (t <sub>P</sub> )	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

#### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)